izmo

January 12, 2026

The Manager Corporate Relationship Department Bombay Stock Exchange Limited Floor 25, Phiroze Jeejeebhoy Tower Dalal Street, Mumbai-400001	The Manager – Listing Department National Stock Exchange of India Limited Exchange Plaza, 5th Floor Plot No. C/1, G Block, Bandra Kurla Complex, Bandra(E), Mumbai-400051
BSE Scrip Code: 532341	**NSE Symbol: IZMO**

Subject: Press Release

Dear Sir/Madam,

Pursuant to the applicable regulations of SEBI (Listing Obligations and Disclosure Requirements) Regulation 2015, we are enclosing Press Release "***izmo Microsystems Achieves Milestone in 3D Space-Grade Packaging; Realizes 84% Footprint Reduction***. The press release is self-explanatory.

The above information shall also be made available on the Company's website www.izmoltd.com

Kindly take the same on record and acknowledge.

Yours faithfully,
For **IZMO Limited**

VARUN KUMAR SRIDHARA ADGUR
Digitally signed by VARUN KUMAR SRIDHARA ADGUR
Date: 2026.01.12 09:25:39 +05'30'

Varun Kumar A S
Company Secretary and Compliance Officer

Encl: As Above

izmoltd.

BUSINESS UPDATE RELEASE

izmo Microsystems Achieves Milestone in 3D Space-Grade Packaging; Realizes 84% Footprint Reduction

BENGALURU, INDIA — January 12, 2026 — izmo Ltd. (NSE: IZMO) today announced that its specialized division, izmo Microsystems, has successfully designed a **high-complexity 3D System-in-Package (SiP) module** for **Space Payload Camera Electronics**. This achievement leverages an advanced 3D SiP architecture with stacked substrates to meet the reliability standards required for space-grade electronics.

By re-engineering traditional the 200 mm × 200 mm PCB-based electronics into a compact 81 mm × 81 mm SiP module, izmo Microsystems has realized an 84% reduction in footprint. This is achieved through the integration of active components in bare-die form onto a stacked-substrate configuration using high-density wire bonding. This approach enables high routing density and multi-function integration while maintaining the compact dimensions necessary for space-constrained environments.

The module is enclosed in a fully indigenized custom Hermetic Ceramic Package, designed and fabricated in India. This hermetic solution is engineered for the environmental robustness and long-term performance essential for the extreme thermal and vacuum conditions of space. Mastering this level of integration is a significant technical hurdle, as it requires managing high-density signal integrity and thermal dissipation within a small volume.

This achievement represents a **major advancement in India's semiconductor mission** and the **"Make in India" initiative**. While standard SiP solutions typically focus on commercial electronics, izmo Microsystems' achievement represents a shift into advanced 3D heterogeneous integration for space electronics.

This capability is currently held by only a **select group of global Tier-1 aerospace firms**. By indigenously developing 3D vertical stacking and hermetically sealed ceramic packages, izmo Microsystems significantly reduces reliance on restricted foreign technologies for mission-critical applications. This milestone establishes a sovereign technical foundation in India for the future of Silicon Photonics and Quantum Communications, where traditional packaging methods are insufficient.

Dinanath Soni, Executive Director of izmo Microsystems Pvt. Ltd., stated: "*The successful realization of this 3D SiP module validates our technical roadmap and our ability to execute on highly complex semiconductor packaging requirements. By migrating space electronics to integrated 3D architectures, we provide a viable solution for the 'NewSpace' industry where mass and volume reduction are critical factors. This achievement confirms our end-to-end competency in space-grade miniaturization and our commitment to building high-value intellectual property within India.*"

Global Market Landscape

The advancement of SiP technology is a growing trend in the global semiconductor industry, with the broader System-in-Package market and space electronics sector valued at over **$20 billion** and **$10 billion** respectively. The growth of SiP is driven by the need for heterogeneous integration in cutting-edge sectors such as Silicon Photonics, where optical and electronic components must be placed in close proximity, as well as in Power Electronics and Radio Frequency (RF) applications. izmo Microsystems is now positioned within this shifting global landscape for advanced semiconductor solutions.

About izmo Microsystems

izmo Microsystems, a division of izmo Ltd. (NSE: IZMO), specializes in advanced IC packaging and silicon photonics solutions. The company provides design and manufacturing services for the aerospace, defense, and electronics sectors and is the exclusive industry partner of the Centre of Excellence for Programmable Silicon Photonics ICs (COE CPPICS) at IIT Madras.

For more information, please contact:

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